

MAPESONIC CR

Thin section soundproofing membrane to combat the noise of footsteps transmitted through floor slabs, applied before laying ceramic, stone, resilient and multi-layered parquet floors



WHERE TO USE

Under-floor soundproofing system applied in a thin layer to counteract the transmission of noise through floors caused by footsteps.

Mapesonic CR has been specifically developed for application in existing buildings to improve soundproofing without removing the floors and screeds.

It is particularly suitable, therefore, for all buildings (residential units, hotels, offices, rest-homes, schools, etc.) under renovation.

Some application examples

Mapesonic CR may be used:

for laying ceramic flooring (also of large format) and stone material

for laying multi-layered parquet, laminate and floating parquet

for laying resilient floors (PVC, rubber, linoleum)

TECHNICAL CHARACTERISTICS

Mapesonic CR is manufactured using recomposed cork and rubber bound together with high-quality polyurethane composite.

ADVANTAGES

- High acoustic performances
- Uncoupling and anti-fracture properties
- Can be used without removing existing flooring
- Low thickness (2 and 4 mm)
- Applicable above radiant floors
- Suitable for the main types of flooring
- Does not require the use of special adhesives
- Environmentally friendly (recycled and recyclable raw materials)
- Very low emission of volatile organic substances (VOC)
- Helps earn LEED certification credits

RECOMMENDATIONS

- Only apply on horizontal internal surfaces.
- Do not apply in areas subject to heavy traffic and in the presence of high concentrated loads. In case of doubt, please contact the MAPEI Technical Services Department.
- Do not apply under lightweight or shiny resilient floor coverings or under cushion-floor.
- Apply **Mapesonic Strip** around the perimeter to avoid the formation of acoustic bridges.
- Do not expose the material to direct sunlight.
- If accidental contact with water is possible (e.g. application in bathrooms etc.), bond **Mapesonic CR** using **Ultrabond Eco S948 1K** and protect it using **Mapelastic Smart** or **Mapelastic Turbo** reinforced with **Mapenet 150**.
- When applying the product to cementitious substrates ensure they are completely cured.
- Do not apply on floors to be polished in situ.
- Make sure the product is applied on solid substrates.
- Do not apply on substrates subject to continuous rising damp.

PREPARATION OF THE SUBSTRATE

Mapesonic CR may be applied on all types of cementitious or anhydrite substrates as long as they are well cured, mechanically strong, coherent, dry, flat, have no cracks and are free of dust and other material which could compromise adhesion.

Cracks may be repaired with products such as **Eporip**, **Eporip Turbo** or **Epojet**.

If the moisture content in cementitious substrates is higher than the required level, wait sufficient time until it dries or apply a waterproofing primer such as **Eco Prim PU 1K**, **Primer MF**, **Triblock P**, **Primer PU 60**, etc. to form a suitable vapour barrier.

Mapesonic CR may be laid on old ceramic and stone, floor coverings as long as they are well bonded to the substrate and have been cleaned to remove traces of grease, oil, wax, varnish, etc.

On uneven surfaces and areas where fittings pass through (such as electric cables and pipe-work) the substrate must be levelled before laying **Mapesonic CR**.

To even out laying surfaces please refer to the catalogues which illustrate the various ranges of MAPEI products for the preparation of substrates or contact the MAPEI Technical Services Department.

APPLICATION PROCEDURE

Before removing the protective plastic backing sheet, apply **Mapesonic Strip** adhesive tape around the perimeter of the room and around pillars and all other abutments.

The product must be laid in a continuous layer, with special care at the corners of the room and at the joints between sections.

Mapesonic Strip can be applied after laying **Mapesonic CR**.

On clean, dry surfaces unroll the sheets of **Mapesonic CR** in the direction of the longest side of the room.

Leave 24 hours to acclimatise before cutting them to size.

Roll the sheets up again to half their length, with the remaining part lying on the substrate, and spread the adhesive dependant on the characteristics of the substrate on the exposed part of the surface and of the floor to be applied.

Ultrabond Eco V4 SP can be used on absorbent substrates, such as screeds and smoothing and levelling compounds.

One of the one-component adhesives based on sililated or two-component polyurethane or epoxy-polyurethane based adhesives of the MAPEI range must be used on non-absorbent substrates, such as ceramic tiles, and for application of multi-layered parquet.

C2 S1 cementitious adhesives can be used to glue **Mapesonic CR** before application of ceramic tiles and stone materials.

After laying the sheet, massage the surface with a rigid roller or flat trowel, starting from the centre and working towards the edge. Repeat the laying procedure for the second part of the roll.

Do not apply too much pressure on the surface while applying **Mapesonic CR** or until the adhesive used for bonding has completely set.

24-48 hours after laying the sheets, the new floor finish may be bonded.

We recommend using class C2S1 cementitious adhesives, such as **Keraflex Maxi S1 Zero** and **Ultralite S1 Zero** to bond ceramic, porcelain and stone not sensitive to moisture over **Mapesonic CR**.

When bonding stone sensitive to moisture (class B according to the MAPEI classification system), use **Elastorapid** or **Granirapid**.

If other adhesives are used, please contact the MAPEI Technical Services Department.

Parquet floors (multi-layered type only) may be laid with one of the one-component adhesives based on sililated or two-component polyurethane or epoxy-polyurethane based adhesives of the MAPEI range.

When laying resilient floor coatings, we recommend applying a cementitious smoothing and levelling layer of **Nivorapid** (or **Planipatch**) + **Latex Plus** reinforced with **Mapenet 150** to distribute concentrated loads.

Grouting and sealing

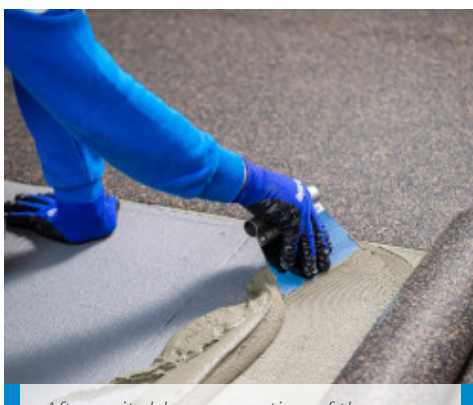
After applying and grouting the new floor finish, cut off the excess part of the **Mapesonic Strip**.

Apply the skirting around the room without coming into direct contact with the floor. Seal the space between the skirting and the floor with a suitable flexible sealant.

To use the aforementioned MAPEI products correctly, please refer to the specific technical data sheet for each product available at our website www.mapei.com.



Apply Mapesonic Strip adhesive tape around the perimeter of the room



After suitable preparation of the substrate, spread on the adhesive to bond the soundproofing sheets



Unroll the sheets of Mapesonic CR on the surfaces to be soundproofed



Massage the surface with a rigid roller or flat trowel, starting from the centre and working towards the edge



Spread the adhesive on Mapesonic CR and bond the new floor finish



Grout the surface of the room



Once the grout has hardened, trim the perimeter of the Mapesonic Strip to remove the excess





Apply the skirting around the room without letting it come into direct contact with the floor



Seal the gap between the skirting board and the floor with a suitable flexible sealant from the Mapei range

SAFETY INSTRUCTIONS FOR PREPARATION AND APPLICATION

Mapesonic CR is an article and referring to the current European regulations (Reg. 1906/2007/CE - REACH) does not require the preparation of the material safety data sheet. During use it is recommended to wear gloves and goggles and follow the safety requirements of the workplace.

PRODUCT FOR PROFESSIONAL USE.

TECHNICAL DATA (typical values)

TECHNICAL DATA	MEASURE UNIT	VALUES	
Thickness	mm	2	4
Length	m	20	10
Width	m	1	1
Thermal resistance	m ² k/W	0.024	0.048
Material	-	Cork and recycled rubber	
Elongation at failure according to EN ISO 1798	%	20	
Tensile strength EN ISO 1798	N/mm ²	0.6	
Cohesion of material under pull off test	N/mm ²	> 0.5	
Emission of volatile organic compounds (VOC)	EMICODE	EC1 Plus very low emissions	
Reduction of impact noise with bonded flooring - ΔL_w	dB	18*	

*Values obtained in the laboratory according to EN ISO 10140-3 by providing for the total gluing of the individual layers to the relative support

WARNING

While the indications and guidelines contained in this data sheet correspond to the company's knowledge and wide experience, they must be considered, under all circumstances, merely as an indication and subject to confirmation only after long-term, practical applications. Therefore, anybody who undertakes to use this product, must ensure beforehand that it is suitable for the intended application and, in all cases, the user is to be held responsible for any consequences deriving from its use.

Please refer to the current version of the Technical Data Sheet, available from our website www.mapei.com

LEGAL NOTICE

The contents of this Technical Data Sheet ("TDS") may be copied into another project-related document, but the resulting document shall not supplement or replace requirements per the TDS in force at the time of the MAPEI product installation.

The most up-to-date TDS can be downloaded from our website www.mapei.com.

ANY ALTERATION TO THE WORDING OR REQUIREMENTS CONTAINED OR DERIVED FROM THIS TDS
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